Binary to 1-8 Decoder (Low)

The MC10161 is designed to decode a three bit input word to a one of eight line output. The selected output will be low while all other outputs will be high. The enable inputs, when either or both are high, force all outputs high.

The MC10161 is a true parallel decoder. No series gating is used internally, eliminating unequal delay times found in other decoders. This design provides the identical 4 ns delay from any address or enable input to any output.

A complete mux/demux operation on 16 bits for data distribution is illustrated in Figure 1. This system, using the MC10136 control counters, has the capability of incrementing, decrementing or holding data channels. When both S0 and S1 are low, the index counters reset, thus initializing both the mux and demux units. The four binary outputs of the counter are buffered by the MC10161s to send twisted—pair select data to the multiplexer/demultiplexer to units.

- $P_D = 315 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 4.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)

LOGIC DIAGRAM E0 2 E1 15 A 7 A 7 A 7 VCC1 = PIN 1 VCC2 = PIN 16 VEE = PIN 8

TRUTH TABLE

ENA INPL		IN	IPUT	S	OUTPUTS							
E1	E0	C	В	Α	Q0	Q1	Q2	Q3	Q4	Q5	Q6	Q7
L	L	-	1	Г	L	Н	Н	Н	Н	Н	Н	Н
L	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
L	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
L	Ļ	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
L	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
L	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
L	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
L	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	Χ	Χ	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
Χ	Ι	Χ	Χ	Χ	Ι	Ι	Ι	Н	Н	Н	Н	Н



ON Semiconductor

http://onsemi.com

MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775

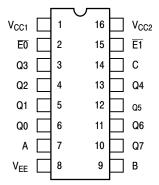


A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping
MC10161L	CDIP-16	25 Units / Rail
MC10161P	PDIP-16	25 Units / Rail
MC10161FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

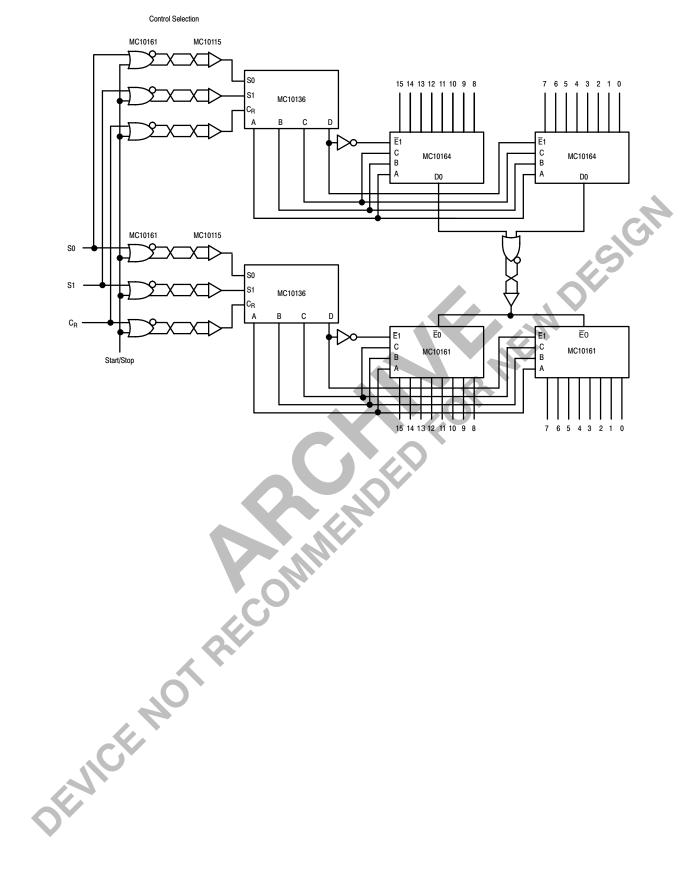
				Test Limits							
			Pin Under	-30)°C		+25°C		+85	5°C	
Characteristic		Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drai	in Current	ΙE	8		84		61	76		84	mAdc
Input Current		I _{inH}	14		350			220		220	μAdc
		I _{inL}	14	0.5		0.5			0.3		μAdc
Output Voltage	Logic 1	V _{OH}	13 13	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage	Logic 0	V _{OL}	13	-1.890	-1.675	-1.850		-1.650	-1.825	-1.615	Vdc
Threshold Voltage	Logic 1	V _{OHA}	13 13	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdc
Threshold Voltage	Logic 0	V _{OLA}	13		-1.655			-1.630		-1.595	Vdc
Switching Times (50Ω Load)										ns
Propagation Delay	,	t ₁₄₊₁₃ - t ₁₄₋₁₃₊	13 13	1.5 1.5	6.2 6.2	1.5 1.5	4.0 4.0	6.0 6.0	1.5 1.5	6.4 6.4	
Rise Time (2	20 to 80%)	t ₁₃₊	13	1.0	3.3	1.1	2.0	3.3	1.1	3.5	
Fall Time (2	20 to 80%)	t ₁₃₋	13	1.0	3.3	1.1	2.0	3.3	1.1	3.5	

ELECTRICAL CHARACTERISTICS (continued)

ELECTRICAL CHAI		(
				TEST VOLTAGE VALUES (Volts)					
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST VC	LTAGE APP	LIED TO PII	NS LISTED B	ELOW	
Characteris	stic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain C	Current	Ē	8	2,7,9,14,15				8	1,16
Input Current		l _{inH}	14	14				8	1,16
		l _{inL}	14		14			8	1,16
Output Voltage	Logic 1	V _{OH}	13 13	2 15				8 8	1,16 1,16
Output Voltage	Logic 0	Vol	13	14				8	1,16
Threshold Voltage	Logic 1	V _{OHA}	13 13			2 15		8 8	1,16 1,16
Threshold Voltage	Logic 0	V _{OLA}	13			14		8	1,16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay	4	t ₁₄₊₁₃ - t ₁₄₋₁₃₊	13 13			14 14	13 13	8 8	1,16 1,16
Rise Time	(20 to 80%)	t ₁₃₊	13			14	13	8	1,16
Fall Time	(20 to 80%)	t ₁₃₋	13			14	13	8	1,16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

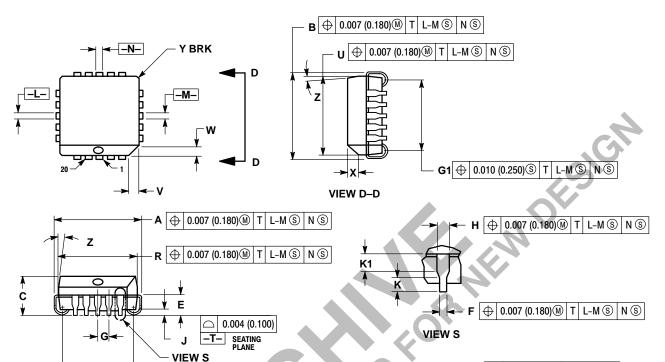
FIGURE 1 — HIGH SPEED 16-BIT MULTIPLEXER/DEMULTIPLEXER



PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- IOTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

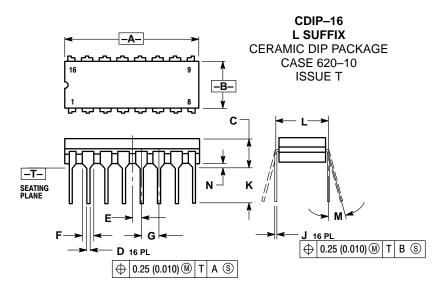
 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y		0.020		0.50
Z	2°	10°	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS



NOTES:

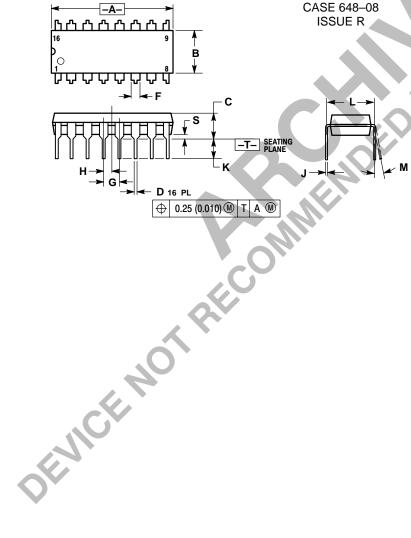
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIN	IETERS		
DIM	MIN	MAX	MIN	MAX		
Α	0.750	0.785	19.05	19.93		
В	0.240	0.295	6.10	7.49		
С		0.200		5.08		
D	0.015	0.020	0.39	0.50		
Е	0.050	BSC	1.27 BSC			
F	0.055	0.065	1.40	1.65		
G	0.100	BSC	2.54 BSC			
Н	0.008	0.015	0.21	0.38		
K	0.125	0.170	3.18	4.31		
L	0.300	BSC	7.62 BSC			
M	0 °	15°	0 °	15°		
N	0.020	0.040	0.51	1.01		

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
C	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

Notes



Notes





ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 **Email**: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.